

GainForce Technology Co.,Ltd

嘉光科技股份有限公司

承認書

APPROVAL SHEET

品 名： Multilayer Chip Antenna

MODEL NAME _____

料 號： AT7020-E3R0HBA/LF

PART NUMBER _____

客戶名稱： 欣 技

CUSTOMER _____

供 應 商： GainForce

VENDOR _____

使用機種： _____

MODEL _____

聯 絡 人： 古 芳 瑜

聯絡電話： (02) 8221-6858

附 件：

ACCESSORIES

規格書

樣品

SPECIFICATION

SAMPLE

圖樣

檢驗報告

DRAWING

TEST REPORT

認可狀況：

(APPROVED STATUS)

AT7020 Series

Multilayer Chip Antenna

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ Wide bandwidth

Applications

- ❖ 2.4GHz WLAN, Home RF, Bluetooth Modules, etc.



Specifications

Part Number	Frequency Range (MHz)	Peak Gain (dBi typ.)	Average Gain (dBi typ.)	VSWR	Impedance
AT7020-E3R0HBA_	2400~2500	1.3dBi (XZ-V)	-0.5dBi (XZ-V)	2 max.	50 Ω

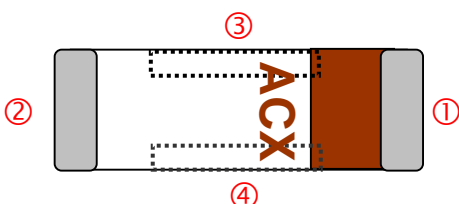
Q'ty/Reel (pcs) : 1,000 pcs
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : -40 ~ +85 °C
 Power Capacity : 3W max.

Part Number

AT **7020** - **E** **3R0** **HBA**  **/LF**
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	AT : Antenna	② Dimensions (L x W)	7.0x 2.0 mm
③ Material Code	E	④ Frequency Range	3R0=3000MHz
⑤ Specification Code	HBA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	=lead-containing /LF=lead-free		

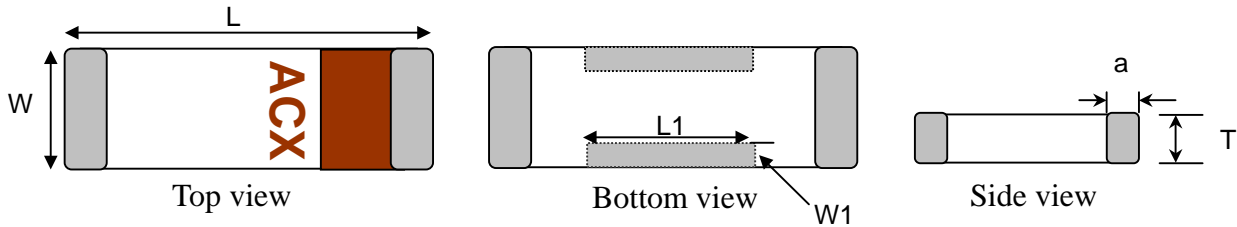
Terminal Configuration



No.	Terminal Name	No.	Terminal Name
①	Feeding Point	③	NC
②	NC	④	NC

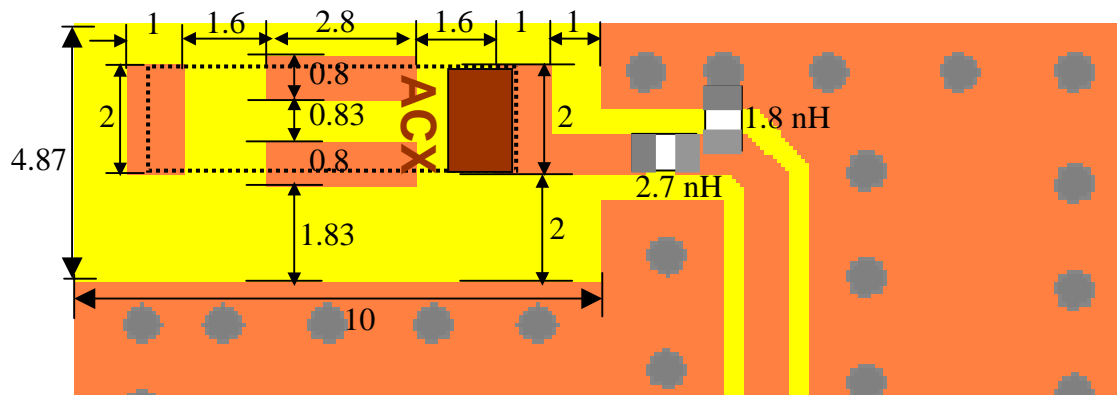
Dimensions and Recommended PC Board Pattern

Unit : mm



Mark	L	W	L1	W1	T	a
Dimensions	7.0 ± 0.2	2.0 ± 0.2	2.6 ± 0.2	0.5 ± 0.2	$2.0^+_{0.1/-0.2}$	0.5 ± 0.3

❖ With Matching Circuits (Unit in mm)

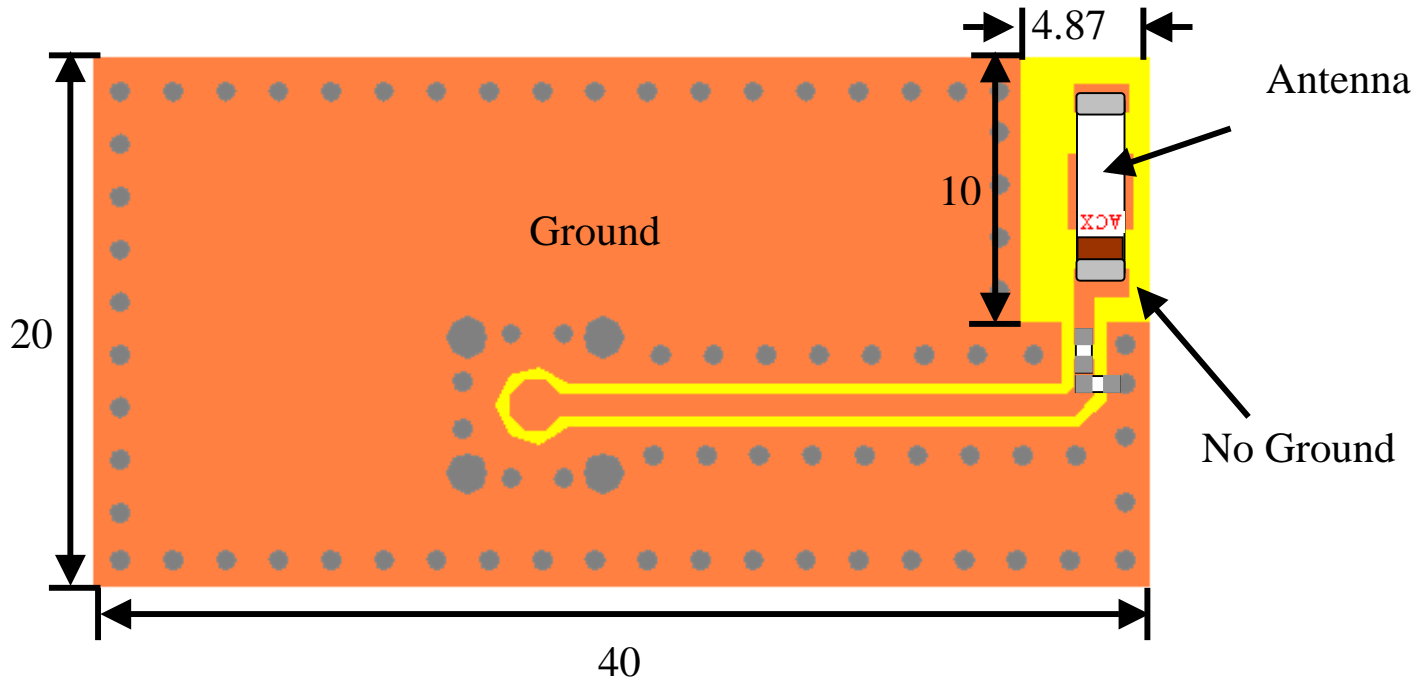


(Matching circuit and component values will be different, depending on PCB layout)

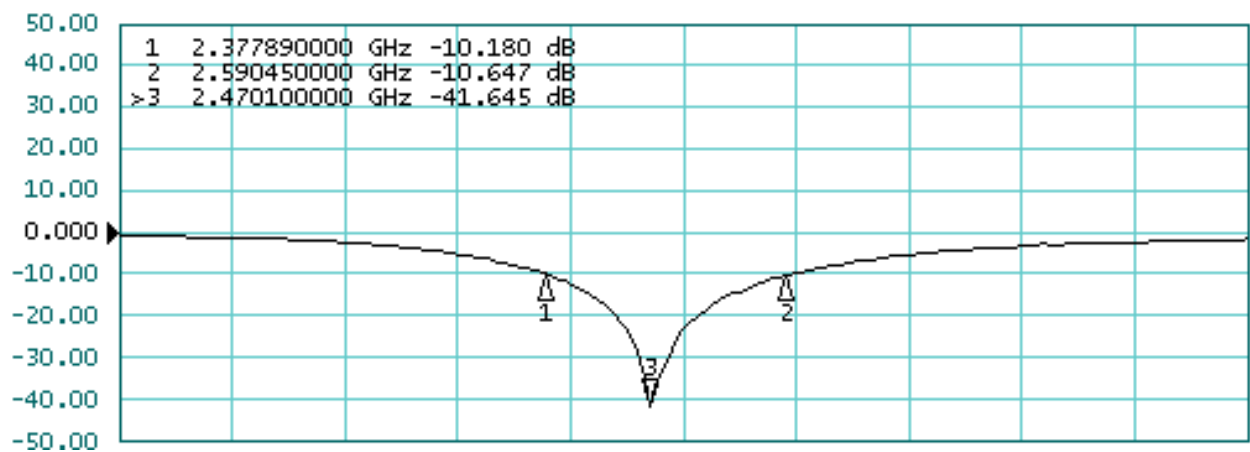
*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

Typical Electrical Characteristics (T=25°C)

❖ Test Board (Unit in mm)

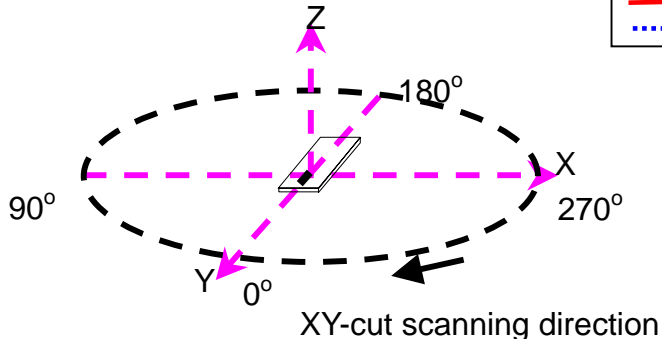


❖ Return Loss/With Matching Circuits

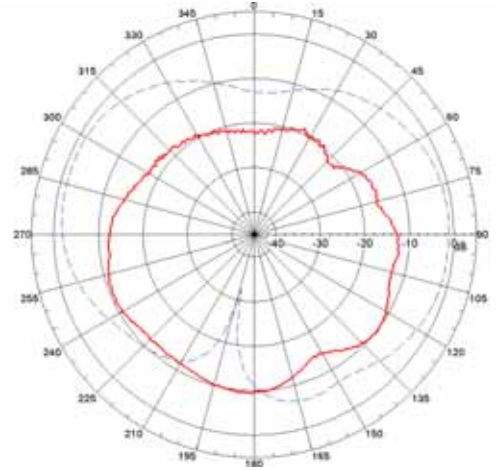


❖ Radiation Patterns

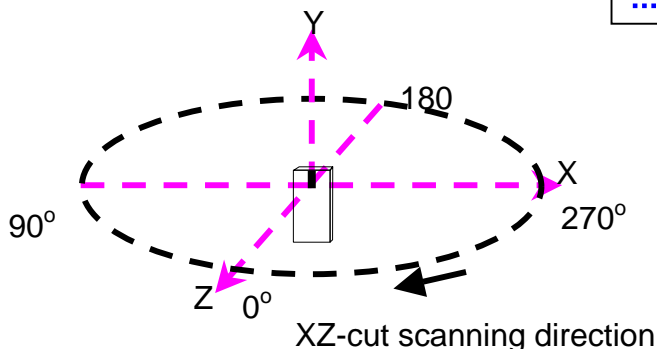
XY-V/XY-H



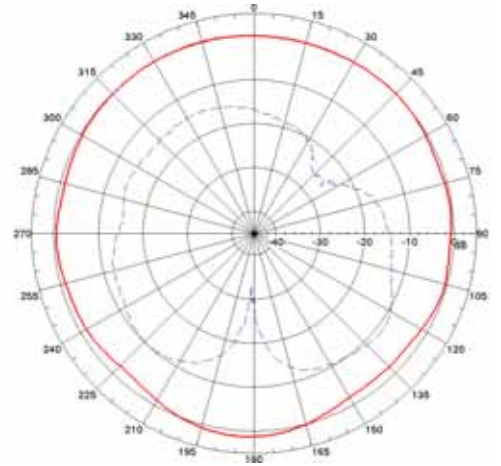
XY cut @2.45GHz
— Vertical
⋯ Horizontal



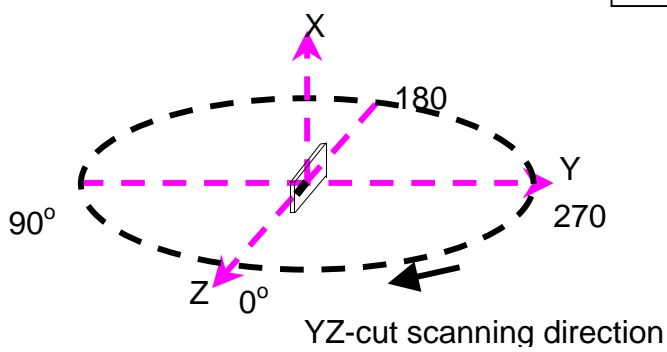
XZ-V/XZ-H



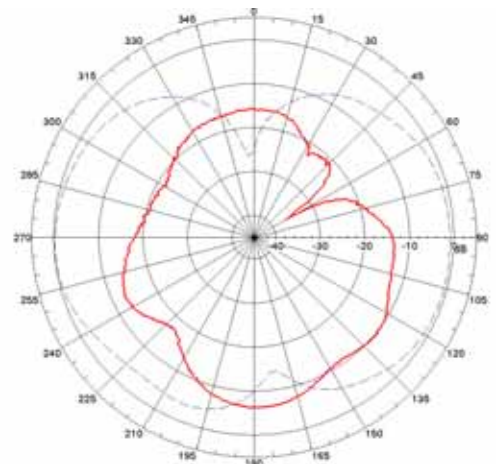
XZ cut @2.45GHz
— Vertical
⋯ Horizontal



YZ-V/YZ-H

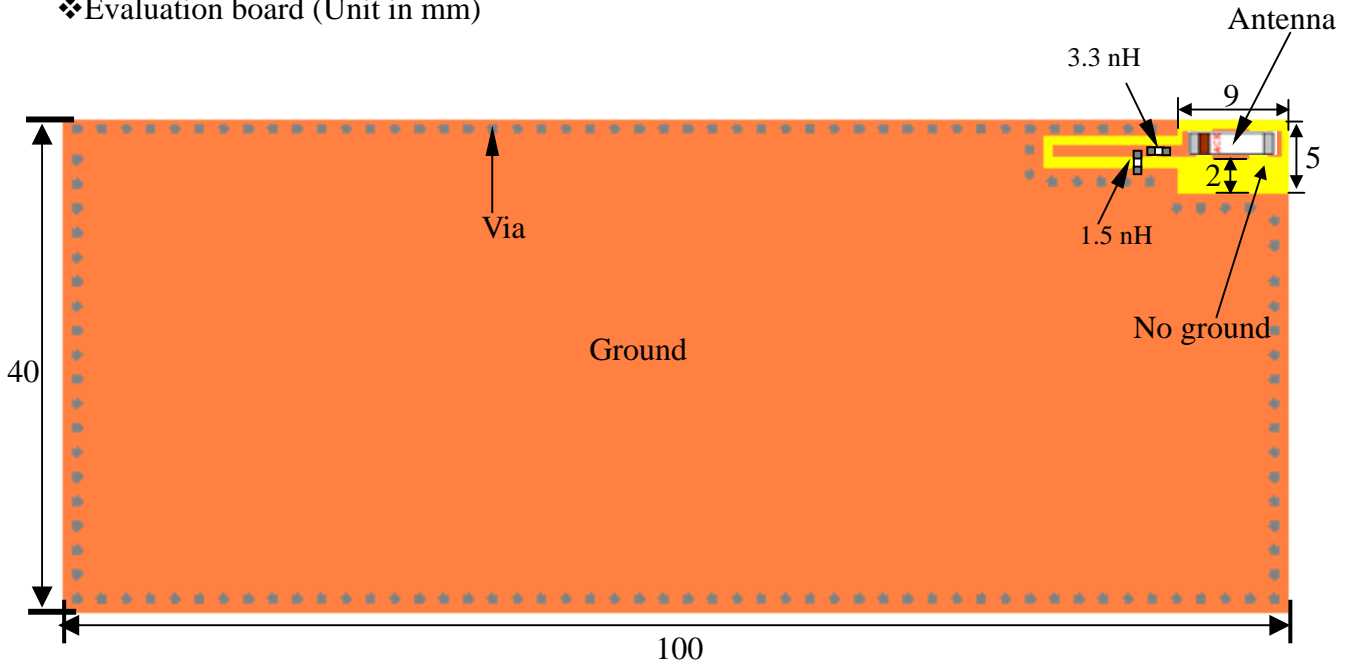


YZ cut @2.45GHz
— Vertical
⋯ Horizontal

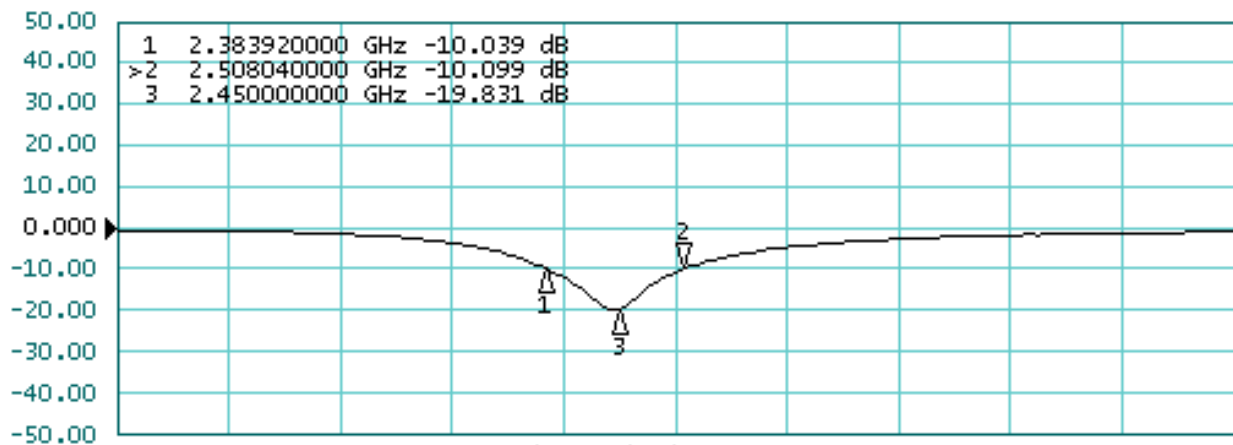


AT7020-E3R0HBA on mobile phone layout

❖ Evaluation board (Unit in mm)

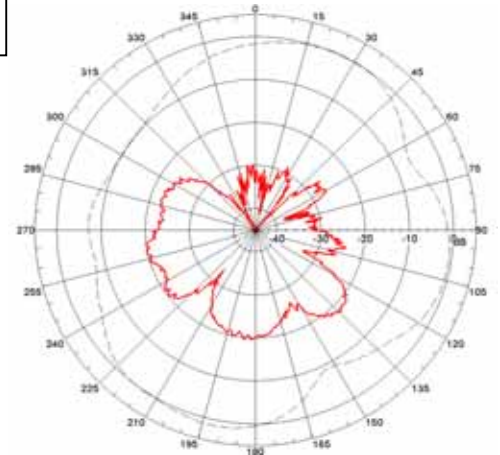
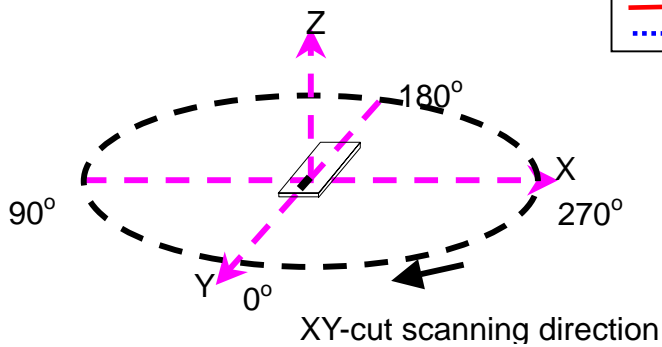


❖ Return Loss/With Matching Circuits

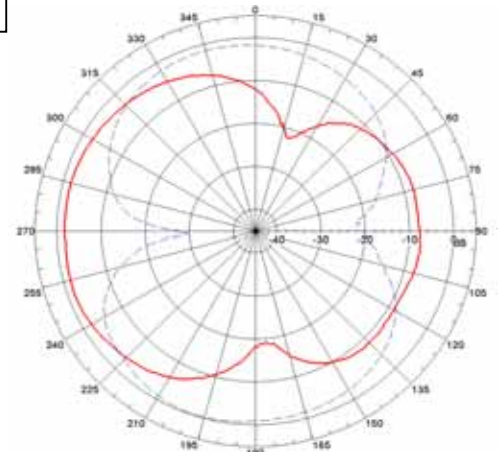
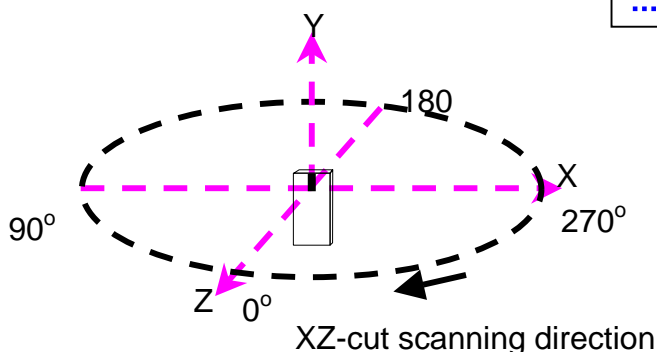


❖ Radiation Patterns

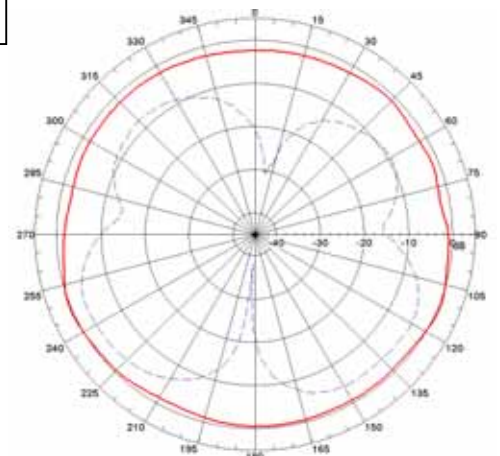
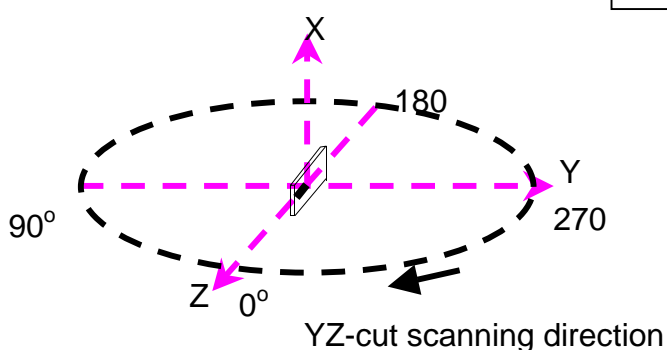
XY-V/XY-H



XZ-V/XZ-H



YZ-V/YZ-H



Advanced Ceramic X Corp.

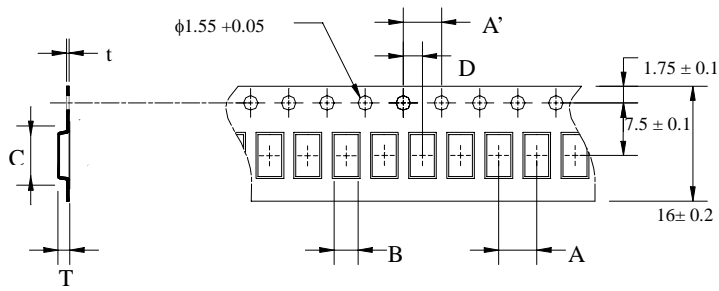
16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan

TEL:886-3-5987008 FAX:886-3-5987001

E-mail: acx@acxc.com.tw <http://www.acxc.com.tw>

Taping Specifications

❖ Tape Dimensions (Unit: mm)

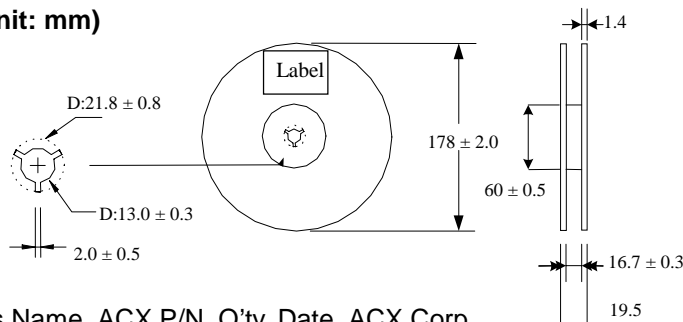


Type	A	A'	B	C	D	t	T
3216	4.0±0.1	4.0±0.1	1.9±0.1	3.5±0.1	2.0±0.1	0.20±0.05	Max. 1.4
5020	4.0±0.1	4.0±0.1	2.4±0.1	5.5±0.1	2.0±0.1	0.20±0.05	Max. 1.4
7020	4.0±0.1	4.0±0.1	2.4±0.1	7.3±0.1	2.0±0.1	0.22±0.05	Max. 1.55
7635	8.0±0.1	4.0±0.1	3.75±0.1	7.85±0.1	2.0±0.1	0.30±0.05	Max. 1.40
8516	4.0±0.1	4.0±0.1	1.85±0.1	8.70±0.1	2.0±0.1	0.25±0.05	Max. 1.40
9520	4.0±0.1	4.0±0.1	2.3±0.1	9.7±0.1	2.0±0.1	0.22±0.05	Max. 1.45
R130	8.0±0.1	4.0±0.1	3.35±0.1	10.35±0.1	2.0±0.1	0.25±0.05	Max. 1.40

❖ Quantity

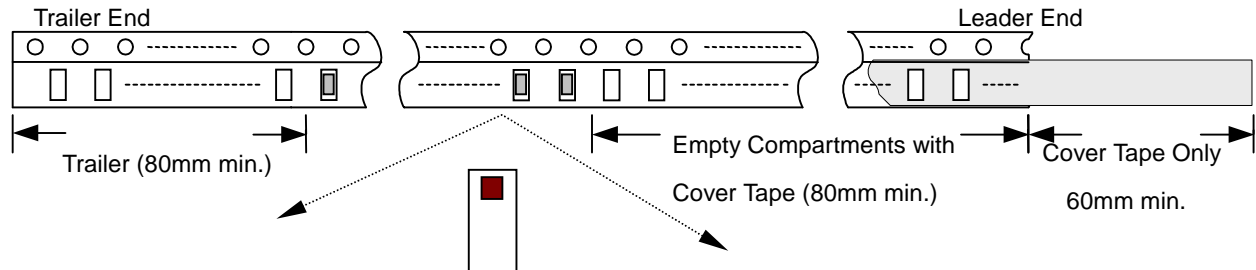
Type	3216	5020	7020	7635	8516	9520	R130
Quantity /per reel	3,000pcs	2,000	1,000 pcs	1,000 pcs	1000pcs	1,000 pcs	1,000 pcs

❖ Reel Dimensions (Unit: mm)

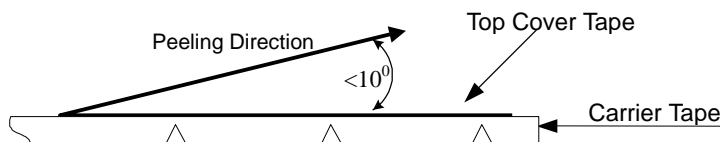


Label: Customer's Name, ACX P/N, Q'ty, Date, ACX Corp.

❖ Leader and Trailer Tape (Plastic material)



❖ Peel-off Force



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300±10 mm/min .

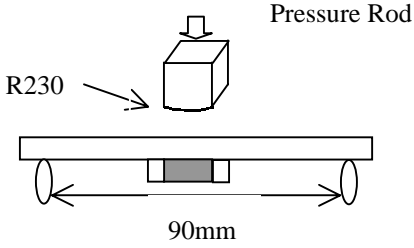
❖ **Storage Conditions**

- (1) Temperature: 15 ~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment
- (3) Products should be used within six months of receipt.

Notes

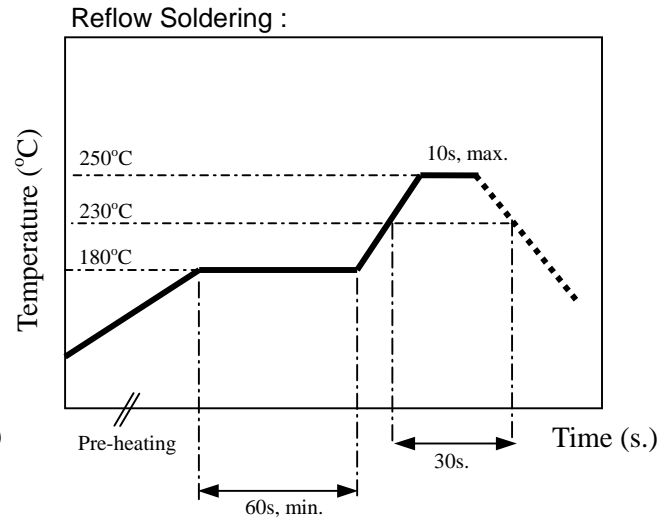
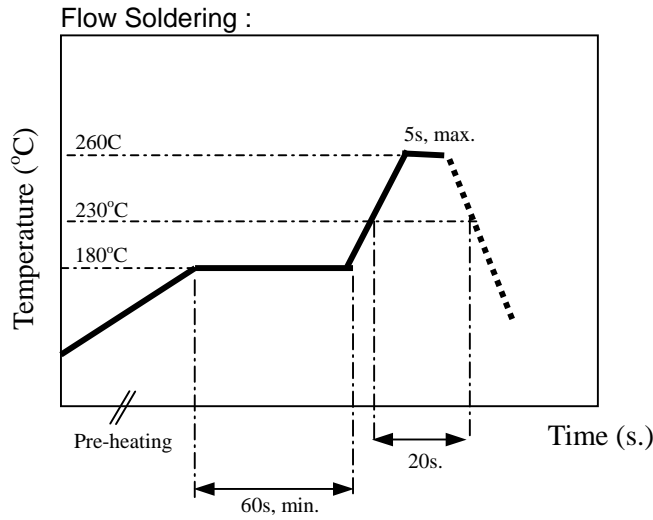
❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

Mechanical & Environmental Characteristics

	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 75% of the terminal electrode shall be covered with new solder 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $230 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/ step 1: $85 \pm 5^\circ\text{C}$ for 20sec step 2: $-40 \pm 3^\circ\text{C}$ for 20sec Cycle time: 30min No. of cycles: 100 Recovery: 1-2hrs
Heat Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Duration: 24 ± 2hrs Recovery: 1-2hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 24 ± 2hrs Recovery: 1-2hrs
Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 80% ~ 85% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Soldering strength (Push strength)	<ol style="list-style-type: none"> 9.8N minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Bending)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection 
Drop Shock	<ol style="list-style-type: none"> No apparent damage 	<ol style="list-style-type: none"> Dropped onto hard wood from height of 50 cm for 3 times ; each x,y and z direction except terminal direction

Typical Soldering Profile

❖ Typical Soldering Profile for Lead-free Process



The sample must be pre-heated before soldering .The temperature difference between preheating and soldering must be within 150 °C.

Notes

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